2.0x1.25mm SMD CHIP LED LAMP



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

KPTK-2012VGC

GREEN

Features

- •2.0mmx1.25mm SMT LED, 0.75mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACK LIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE : 2000PCS / REEL.

Description

The Green source color devices are made with InGaN on SiC Light Emitting Diode.

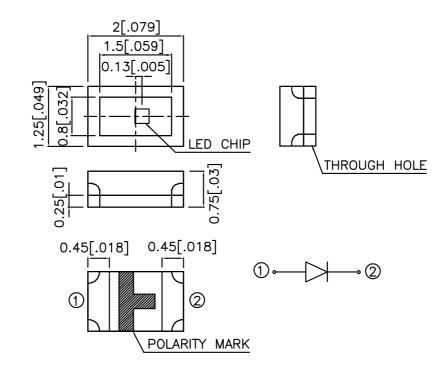
Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or

anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is ±0.1(0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

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Selection Guide					
Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	201/2
KPTK-2012VGC	GREEN (InGaN)	WATER CLEAR	70	200	100 °

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at TA=25°C

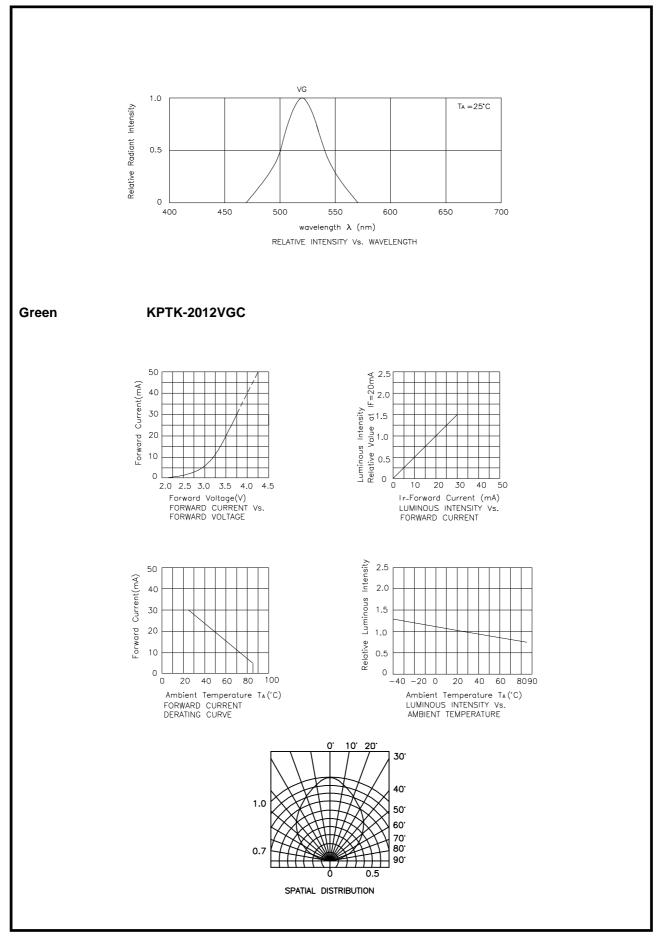
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	IF=20mA
λD	Dominant Wavelength	Green	525		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	38		nm	IF=20mA
С	Capacitance	Green	45		pF	VF=0V;f=1MHz
VF	Forward Voltage	Green	3.5	4.5	V	IF=20mA
IR	Reverse Current	Green		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	105	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating / Storage Temperature	-40°C To +85°C		

Note:

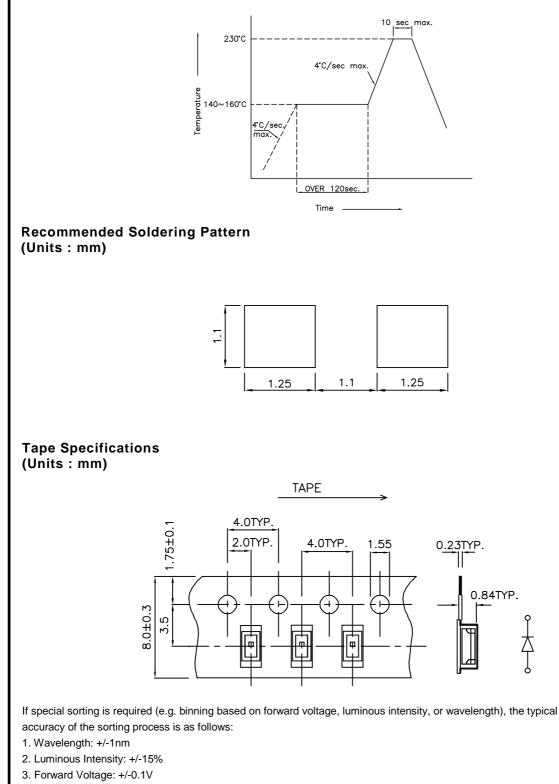
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



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KPTK-2012VGC SMT Reflow Soldering Instructions

Number of reflow process shall be 2 times or less and cooling process to normal temperature is required between first and second soldering process.



Note: Accuracy may depend on the sorting parameters.

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